

2SK1404 Silicon N Channel MOS FET

REJ03G0944-0300 Rev.3.00 May 15, 2006

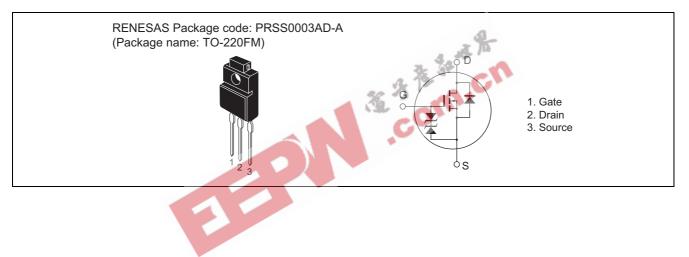
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





Absolute Maximum Ratings

			(1a = 25 C)
Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	600	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	ID	5	A
Drain peak current	I _{D(pulse)} *1	20	A
Body to drain diode reverse drain current	I _{DR}	5	A
Channel dissipation	Pch ^{*2}	35	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at $T_C = 25^{\circ}C$

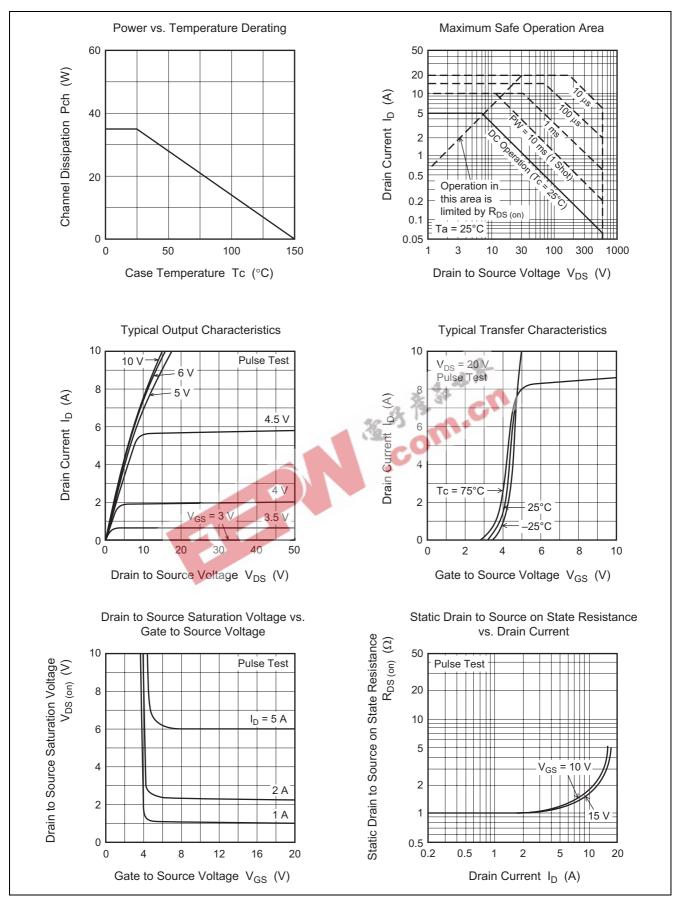
Electrical Characteristics

						$(Ta = 25^{\circ}C)$
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	V _{(BR)DSS}	600	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	V _{(BR)GSS}	±30	_	—	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{DS} = 500 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	2.0	_	3.0	V	$I_{D} = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static drain to source on state	R _{DS(on)}	_	1.1	1.5	Ω	$I_{\rm D}$ = 2.5 A, V _{GS} = 10 V * ³
resistance			- %C	2		
Forward transfer admittance	y _{fs}	3.0	5.0	-0	S	$I_D = 2.5 \text{ A}, V_{DS} = 10 \text{ V}^{*3}$
Input capacitance	Ciss	-	10 00	0	pF	$V_{DS} = 10 V, V_{GS} = 0,$
Output capacitance	Coss	-+	250	_	рF	f = 1 MHz
Reverse transfer capacitance	Crss		45	—	рF	
Turn-on delay time	t _{d(on)}		12	—	ns	$I_D = 2.5 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	tr	-	45	—	ns	$R_L = 12 \Omega$
Turn-off delay time	t _{d(off)}	_	105	—	ns	
Fall time	t _f	_	55	_	ns	
Body to drain diode forward voltage	V _{DF}	—	0.9	—	V	I _F = 5 A, V _{GS} = 0
Body to drain diode reverse recovery time	t _{rr}	_	500	_	ns	I _F = 5 A, V _{GS} = 0, di _F /dt = 100 A/μs

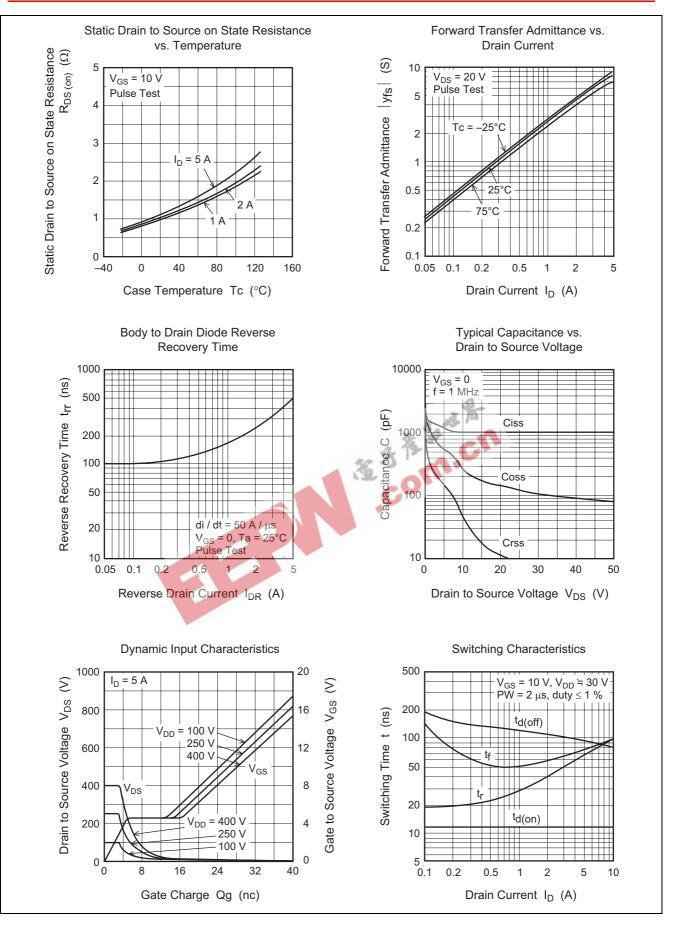
Note: 3. Pulse test



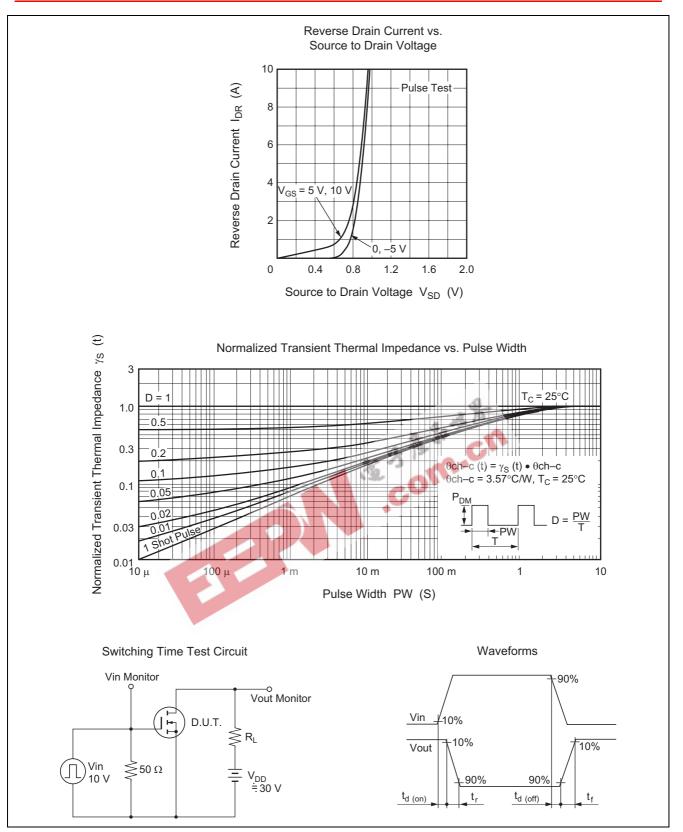
Main Characteristics





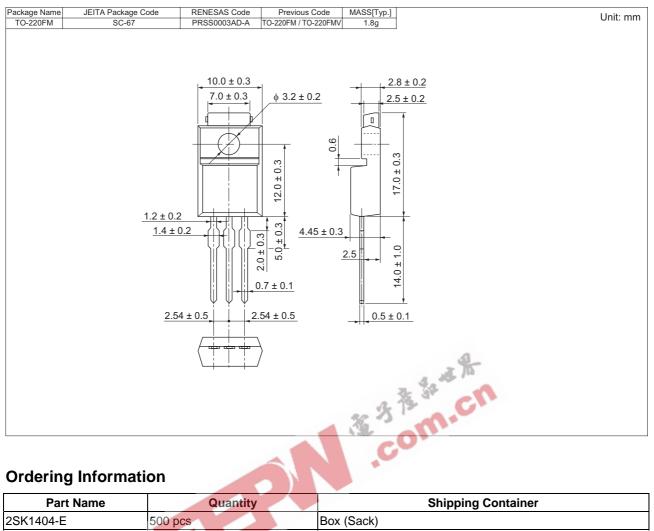








Package Dimensions



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